MAU2728

Silicon epitaxial planar type

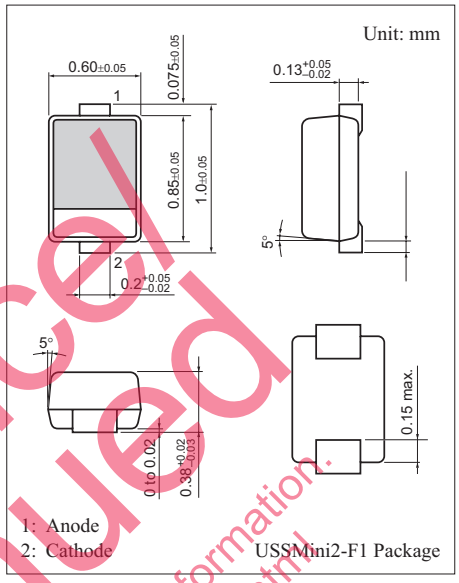
For rectification

■ Features

- Optimum for high-density mounting
- Low forward voltage V_F , good wave detection efficiency η
- Extremely low reverse current I_R

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Maximum peak reverse voltage	V_{RM}	30	V
Forward current (Average)	I_F	30	mA
Non-repetitive peak forward surge current	I_{FSM}	150	mA
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

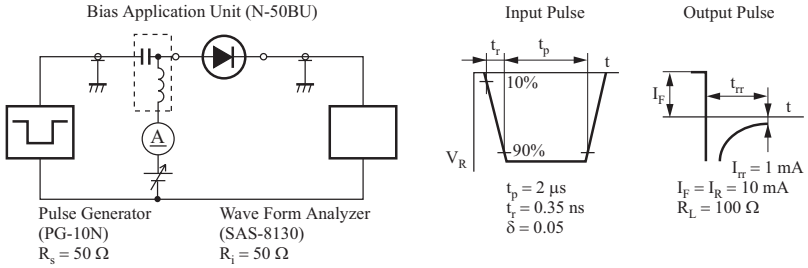


Marking Symbol: 1A

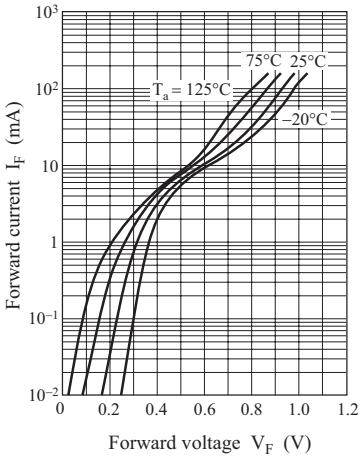
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 1$ mA			0.4	V
	V_{F2}	$I_F = 30$ mA			1.0	V
Reverse current	I_R	$V_R = 30$ V			300	nA
Terminal capacitance	C_t	$V_R = 1$ V, f = 1 MHz		1.5		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 10$ mA, $I_{rr} = 1$ mA, $R_L = 100\ \Omega$		1.0		ns
Detection efficiency	η	$V_{IN} = 3$ V(peak), f = 30 MHz, $R_L = 3.9$ kΩ, $C_L = 10$ pF		65		%

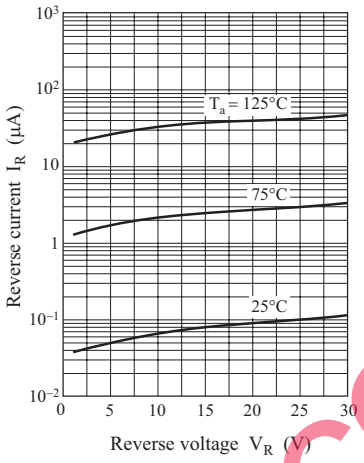
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 2 GHz
4. *: t_{rr} measurement circuit



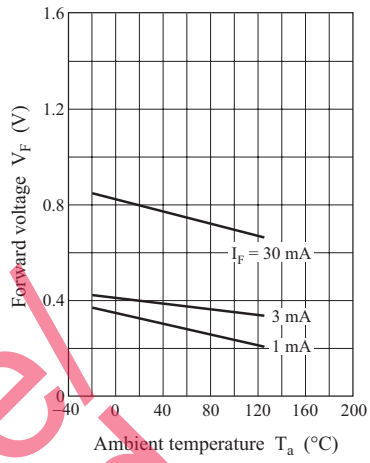
I_F — V_F



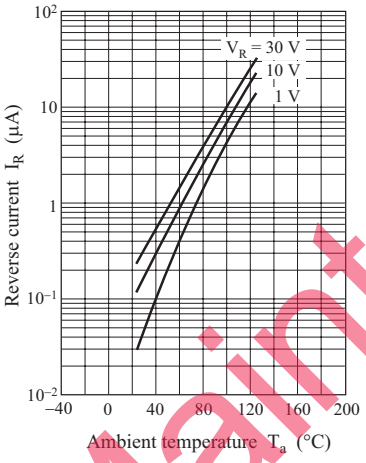
I_R — V_R



V_F — T_a

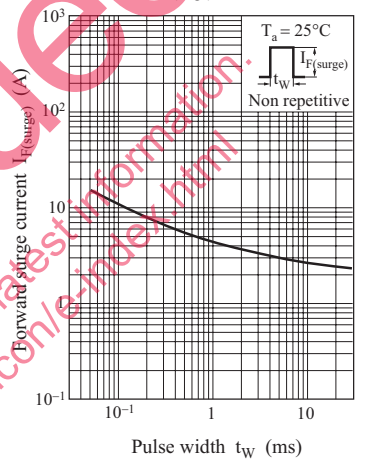


I_R — T_a



C_t — V_R

$I_{F(surge)}$ — t_W



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